

The following listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

Claims 1-15. (canceled)

16. (currently amended) A process for ~~the production of~~ producing a solid first sheet material, comprising ~~the step of~~ heating and applying pressure to:
- (a) a multilayer sheet structure comprising at least one second sheet layer comprising a nonwoven fabric of short high tensile modulus fibers and at least one other sheet layer comprising a thermoplastic polymer having a low moisture absorption; and
- or
- ~~at least one third sheet comprising a nonwoven fabric of a short high tensile modulus fiber and at least one fourth sheet comprising a thermoplastic polymer; and~~
- (b) at least one metal sheet layer;
- wherein said solid sheet has an apparent density and a calculated density, to form wherein said thermoplastic polymer liquid crystalline polymer fills essentially all an effective amount of voids between said high tensile modulus fibers so that said solid sheet has an apparent density that which is at least about 75% of its the calculated density.
17. (previously presented) The process as recited in claim 16 wherein said apparent density is at least about 90% of said calculated density.
18. (previously presented) The process as recited in claim 17 wherein said thermoplastic polymer is a liquid crystalline polymer or a perfluoropolymer.
19. (previously presented) The process as recited in claim 16 wherein said high tensile modulus fiber is an aramid.
20. (previously presented) A circuit board produced by the process of claim 16.

21. (new) The process as recited in claim 18 wherein said thermoplastic polymer is a liquid crystalline polymer.
22. (new) A process for producing a solid sheet comprising heating and applying pressure to:
 - (a) a single layer sheet structure comprising a nonwoven fabric of a short high tensile modulus fiber and a thermoplastic polymer; and
 - (b) at least one metal sheet layer;wherein said solid sheet has an apparent density and a calculated density, wherein said thermoplastic polymer fills an effective amount of voids between said high tensile modulus fibers so that said solid sheet has an apparent density that is at least about 75% of the calculated density.
23. (new) The process as recited in claim 22 wherein said apparent density is at least about 90% of said calculated density.
24. (new) The process as recited in claim 23 wherein said thermoplastic polymer is a liquid crystalline polymer or a perfluoropolymer.
25. (new) The process as recited in claim 24 wherein said thermoplastic polymer is a liquid crystalline polymer.
26. (new) The process as recited in claim 22 wherein said high tensile modulus fiber is an aramid.
27. (new) A circuit board produced by the process of claim 22.